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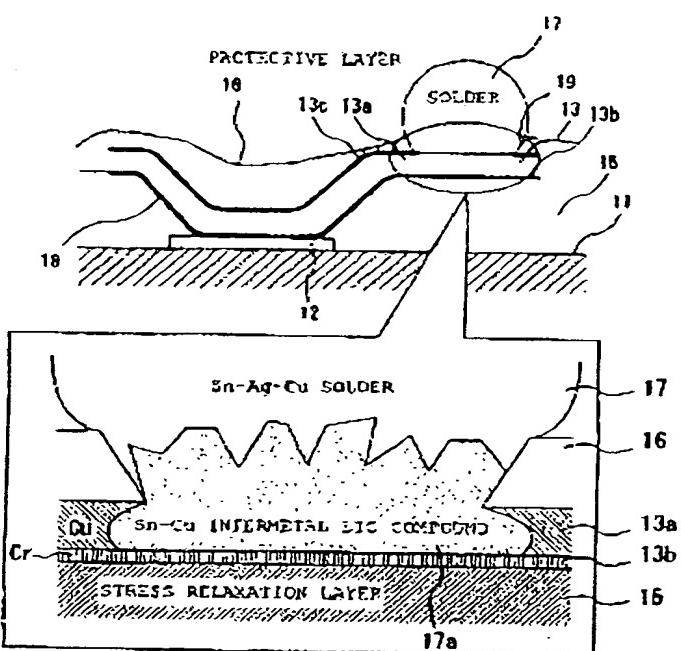
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WO00052755

WIRING BOARD AND ITS PRODUCTION METHOD, SEMICONDUCTOR DEVICE AND ITS PRODUCTION METHOD, AND ELECTRONIC APPARATUS

HITACHI, LTD.

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Application No. JP0000695 JP, Filed 20000209, A1 Published 20000908

Abstract: A high-density wiring board having a high connection reliability and produced at low cost. The wiring board is characterized by comprising a board having an electrode and covered with an insulating layer in which a hole is made so as to expose the electrode, a wiring connected to the electrode and formed of a layer adhering to the insulating layer and made of Cr or Ti and a layer adhering to the Cr or Ti layer and made of Cu, a protective film covering the wiring and having therein a hole for soldering, and solder for external connection formed in the hole by diffusion-alloying the Cu layer and reaching the Cr or Ti layer for establishing

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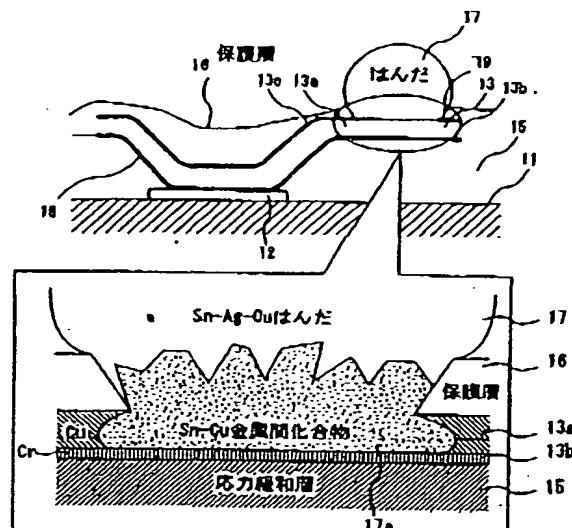
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(57) Abstract

A high-density wiring board having a high connection reliability and produced at low cost. The wiring board is characterized by comprising a board having an electrode and covered with an insulating layer in which a hole is made so as to expose the electrode, a wiring connected to the electrode and formed of a layer adhering to the insulating layer and made of Cr or Ti and a layer adhering to the Cr or Ti layer and made of Cu, a protective film covering the wiring and having therein a hole for soldering, and solder for external connection formed in the hole by diffusion-alloying the Cu layer and reaching the Cr or Ti layer for establishing connection.



16...PROTECTIVE LAYER
17...SOLDER
18...Sn-Ag-Cu SOLDER
19...Sn-Cu INTERMETALIC COMPOUND
15...STRESS RELAXATION LAYER